

Datasheet revision 1.3

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Heat Sink Compound - Grey Ultra Max™ Conductive 10g Syringe 3cc

Product Highlights

- Lead-Free / RoHS 3 Compliant / REACH Compliant
- Ultra Max[™] High-Density Thermal Paste. Grey, non-curing, flowable, thermally conductive heat sink compound. Heavily filled with heat-conductive metal oxide. Provides extremely high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (4 x 10¹³ ohm-cm)

Specifications

Viscosity: Density: Thermal Conductivity: Thermal Resistance: Electrical Volume Resistivity: Operating Temperature (Continuous): Operating Temperature (Peak): Operating Life: Size:

bhm-cm) 87,000 cP (87,000 mPa·s) 2.5g/cc 8.5 W/m·K 0.03 °C*cm²/W 4 x 10¹³ ohm-cm -40 to 150°C (-40 to 302°F) 200°C (392°F) >8 years *dependent on several factors, test in application to ensure suitability 10g Syringe (3cc)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life >24 months

Stencil Life >7 days @ 20-70% RH 22-28°C (72-82°F)

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m⋅K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G